

Amendments to the Claims

Please amend claims 1, 4, 6, 7 and 9 as follows:

1. (Currently Amended) A semiconductor package comprising:  
a semiconductor chip electrically connected to lead frames;  
outer leads protruding from a surface of the semiconductor package, ~~wherein the outer leads are connected to the semiconductor chip~~ through via holes formed thereat, wherein the outer leads are connected to metal lines and the metal lines are connected to the lead frames; and  
grooves formed at a surface of the semiconductor package, ~~the grooves being connected to expose the metal lines, whereby outer leads of another semiconductor package are connected to the metal lines through the grooves.~~
2. (Original) The semiconductor package of claim 1, wherein the outer leads are disposed opposite to the grooves.
3. (Original) The semiconductor package of claim 1, wherein the semiconductor package is connected to another semiconductor package by inserting the outer leads of the semiconductor package into grooves of another semiconductor package.
4. (Currently amended) A semiconductor package comprising:  
a semiconductor chip electrically connected to lead frames; and  
outer wires protruding from a surface of the semiconductor package, wherein the outer wires are connected to the semiconductor chip through via holes, metal lines and the lead frames connected to the metal lines,  
wherein the semiconductor package is connected to another semiconductor package by interconnecting the outer wires with outer wires of another semiconductor package.

5. (Original) The semiconductor package of claim 4, further comprising supporting structures having a predetermined length, the supporting structures being provided on the surface from which the outer wires protrude.

6. (Currently amended) The semiconductor package of claim 5, wherein positioning holes are provided on another semiconductor package, ~~the supporting structures being inserted into the positioning holes.~~

7. (Currently amended) The semiconductor package of claim [4] 6, wherein the semiconductor package is connected to another semiconductor package by inserting the ~~outer wires~~ supporting structures of the semiconductor package into the positioning holes of another semiconductor package.

8. (Original) The semiconductor package of claim 7, wherein the supporting structures have a length greater than a total length of the interconnected outer wires.

9. (Currently amended) The semiconductor package of claim 6, wherein the ~~supporting~~ supporting structures are inserted into the positioning holes.